



RCE 11375178
PTO/SB/42 (10-01)
U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE
10/15/02

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REQUEST FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL

Address to:
Commissioner for Patents
Box RCE
Washington, DC 20231

Application Number	09/972,178
Filing Date	October 9, 2001
First Named Inventor	H. SHIMOKAWA, et al
Art Unit	1775
Examiner Name	J. J. Zimmerman
Attorney Docket Number	500.38665CX1

This is a Request for Continued Examination (RCE) under 37 C.F.R. § 1.114 of the above-identified application. Request for Continued Examination (RCE) practice under 37 CFR 1.114 does not apply to any utility or plant application filed prior to June 8, 1995, or to any design application. See Instruction Sheet for RCEs (not to be submitted to the USPTO) on page 2.

1. **Submission** required under 37 C.F.R. § 1.114

- a. ☐ Previously submitted
 - i. ☐ Consider the amendment(s)/reply under 37 C.F.R. § 1.116 previously filed on _____
(Any unentered amendment(s) referred to above will be entered).
 - ii. ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on _____
 - iii. ☐ Other _____
- b. ☒ Enclosed
 - i. ☒ Amendment/Reply
 - ii. ☐ Affidavit(s)/Declaration(s)
 - iii. ☐ Information Disclosure Statement (IDS)
 - iv. ☐ Other _____

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2. **Miscellaneous**

- a. ☐ Suspension of action on the above-identified application is requested under 37 C.F.R. § 1.103(c) for a period of _____ months. (Period of suspension shall not exceed 3 months; Fee under 37 C.F.R. § 1.17(i) required)
- b. ☐ Other _____

3. **Fees** The RCE fee under 37 C.F.R. § 1.17 (e) is required by 37 C.F.R. § 1.114 when RCE is filed.

- a. ☒ The Director is hereby authorized to charge the following fees, or credit any overpayments, to Deposit Account No. **01-2135 (Case: 500.38665CX1)**
 - i. ☐ RCE fee required under 37 C.F.R. § 1.17 (e)
 - ii. ☐ Extension of time fee (37 C.F.R. §§ 1.136 and 1.17)
 - iii. ☐ Other _____
- b. ☐ Check in the amount of \$ _____ enclosed
- c. ☒ Payment by credit card (Form PTO-2038 enclosed)

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT REQUIRED

Name (Print/Type)	William I. Solomon	Registration No. (Attorney/Agent)	28,565
Signature	<i>William I. Solomon</i>	Date	October 7, 2002

CERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, Box RCE, Washington, DC 20231, or facsimile transmitted to the U.S. Patent and Trademark Office on the date shown below:

Name (Print/Type)	William I. Solomon	Date	October 7, 2002
Signature			

Burden Hour Statement: This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND Fees and Completed Forms to the following address: Assistant Commissioner for Patents, Box RCE, Washington, DC 20231.

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01 FC:179	740.00 OP
02 FC:102	168.00 OP
03 FC:103	432.00 OP

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500.38665CX1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. SHIMOKAWA, et al.
Serial No.: 09/972,178
Filed: October 9, 2001
For: PB-FREE SOLDER-CONNECTED STRUCTURE AND
ELECTRONIC DEVICE
Group: 1775
Examiner: J. J. Zimmerman

SUBMISSION UNDER 37 CFR 1.114
(AMENDMENT)

Assistant Commissioner for Patents
Washington, D.C. 20231

October 7, 2002

Sir:

Concurrently with the filing of the Request For Continued Examination (RCE)
Transmittal, please further amend the above-identified application as follows:

IN THE CLAIMS:

✓
Please add the following new claims to the application.

C1
-60. An electronic device according to claim 1, wherein said Sn-Bi alloy
layer is directly in contact with said lead or directly in contact with a Cu layer in
contact with said lead, and said Pb-free solder is directly in contact with said Sn-Bi
alloy layer.